

TI 35E – run sheet

MicroChemicals GmbH

nanyte.com/photoresists/ti-35e · last updated 2026-09-10

Thickness: 3–4.5 µm

Softbake: 95 °C · 2 min · hotplate

Exposure dose: 140 mJ/cm²

Post-exposure bake: 115–120 °C · 2 min · hotplate

Flood exposure: 540 mJ/cm²

Develop: Developer AZ 826 MIF (metal-ion-free), or a potassium- or sodium-based developer – AZ 400K diluted 1:4, or AZ 351B · Dilution AZ 400K at 1:4; no dilution is stated for AZ 826 MIF or AZ 351B.

Hardbake: 140–145 °C · 2 min · hotplate